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Susan Sihota - Assistant to Gavin N. Manning

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8-30-02  
C. Blum

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Paper No.: \_\_\_\_\_

**IN THE UNITED STATES PATENT & TRADEMARK OFFICE**

Inventor(s): LEUNG, Albert M.  
Title: GAS PRESSURE SENSOR BASED ON SHORT-DISTANCE HEAT CONDUCTION AND METHOD FOR FABRICATING SAME  
Serial No.: 09/788,437  
Filed: 21 February 2001  
Examiner: Marissa L. FERGUSON Art Unit: 2855  
Date: 26 August 2002

Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

**RESPONSE**

This is in response to the Office Action mailed on 6 June 2002.

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Claims 1-21 and 30-43 are pending in this application.

The Examiner has rejected claims 1-21 and 30-43. The Examiner has expressed the view that those claims are obvious in light of Smith (US patent No. 6,343,514) taken in combination with various other references.

Smith discloses a pressure sensor built on a silicon chip (13). A cavity (14) in the chip is covered by a polysilicon diaphragm (15). The cavity is evacuated. A piezoresistive element (41) contacts the diaphragm. Pressure acting on the diaphragm causes the diaphragm to deflect and this causes piezoresistive element (41) to yield a pressure-varying signal that may be detected. As such, Smith's sensor has a completely different principle of operation from the pressure sensor of this invention. Bond pads (19) are provided on